

CLAIM AMENDMENTS

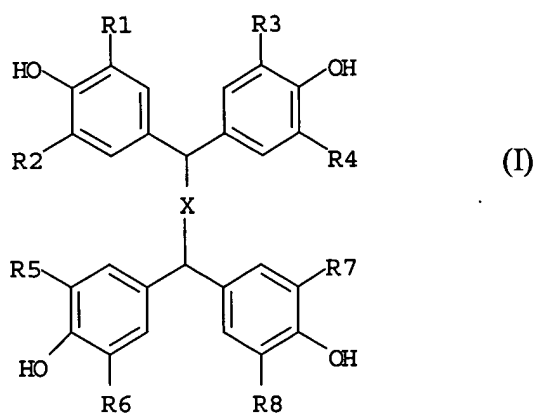
1. - 5. (Cancelled herein)

6. (New) An epoxy resin composition comprising:

an epoxy resin prior to curing,

a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin, and

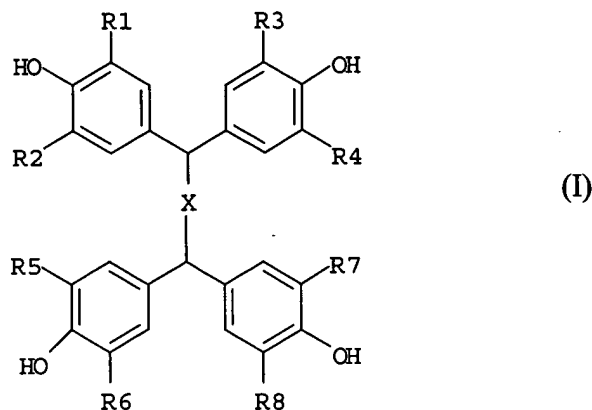
a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

7. (New) The epoxy resin composition according to claim 6, wherein the content of said tetrakisphenol compound represented in formula (I) is a range from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

8. (New) A method for curing an epoxy resin comprising a step of mixing a non-clathrated curing agent reacting with an epoxy group of the epoxy resin to cure the resin and a tetrakisphenol compound represented by a general formula (I) as a curing accelerator catalyst with a non-curing epoxy resin,

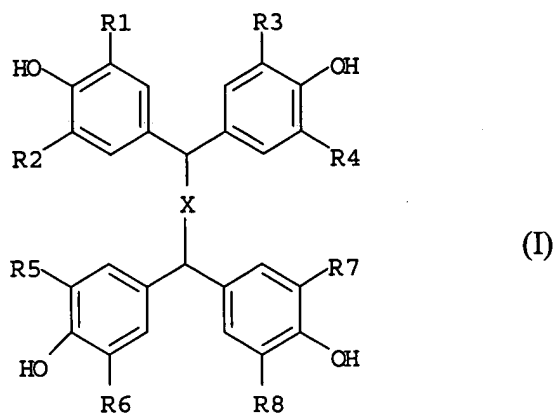


wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

9. (New) The method for curing an epoxy resin according to claim 8, wherein the content of the tetrakisphenol compound represented in general formula (I) is a range from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

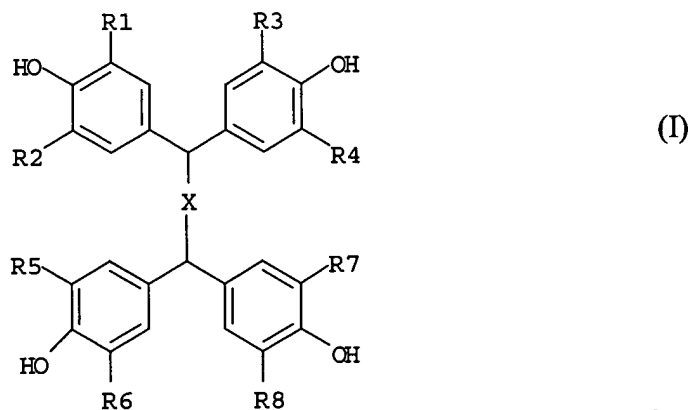
10. (New) A curative for epoxy resin, comprising a clathrate comprising:

a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group to cure an epoxy resin,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

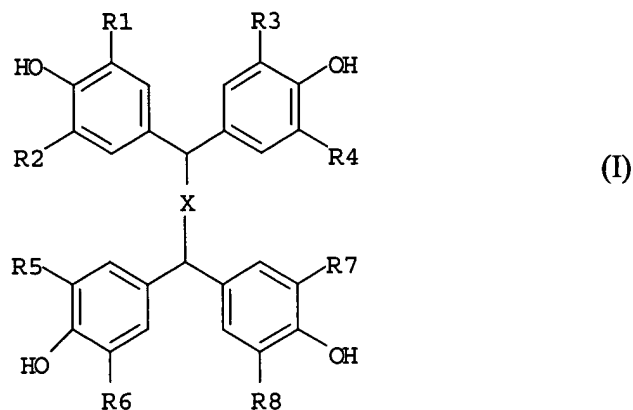
11. (New) A curing accelerator for epoxy resin, comprising a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

12. (New) An epoxy resin composition comprising a non-curing epoxy resin, and a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin; and

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin,

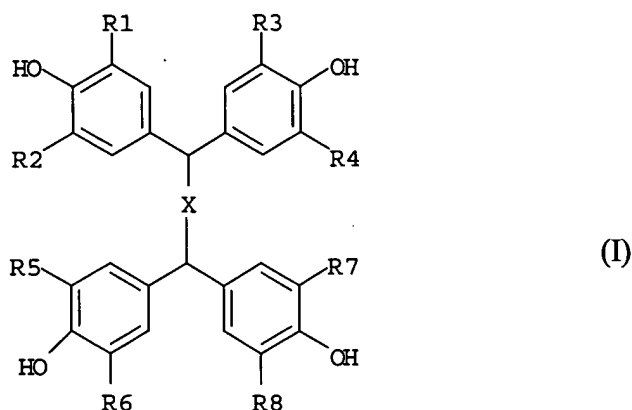


wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

13. (New) The epoxy resin composition according to claim 11, wherein the content of a tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

14. (New) The epoxy resin composition according to claim 12, wherein the content of a tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

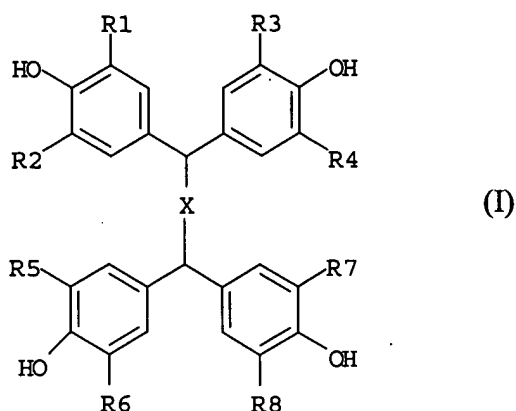
15. (New) A method for curing an epoxy resin composition comprising the steps of:
a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin is added and mixed to a non-curing epoxy resin, and then the mixture is heated to a predetermined temperature,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

16. (New) A method for curing an epoxy resin composition comprising the steps of:
a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound reacting with an epoxy group of the epoxy resin to cure the resin, and

a clathrate comprising a tetrakisphenol compound represented by a general formula (I) and a compound accelerating the curing of a compound reacting with an epoxy group to cure an epoxy resin are added and mixed to a non-curing epoxy resin, and then the mixture is heated to a predetermined temperature,



wherein X represents $(CH_2)_n$, wherein n is 0, 1, 2 or 3, and R^1 to R^8 each represents hydrogen, a lower alkyl, a phenyl optionally substituted with halogen or C_1 - C_6 alkyl, a halogen or a C_1 - C_6 alkoxy.

17. (New) The method for curing an epoxy resin composition according to claim 15, wherein the content of the tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.

18. (New) The method for curing an epoxy resin composition according to claim 16, wherein the content of the tetrakisphenol compound represented by a general formula (I) in the clathrate is in a range of from 0.001 to 0.1 mole based on 1 mole of the epoxy group.